-	44	(glass adj1 (substrate or board)) and (vias or (through adj1	USPAT;	2004/01/06 17:05
		holes)) and filler and ((wir\$ or conductive) adj1 pattern)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	225	(glass adj1 (substrate or board)) and (vias or (through adj1	USPAT;	2004/01/16 09:05
ľ		holes)) and filler	US-PGPUB;	·
			EPO;	
			DERWENT;	
			IBM_TDB	
-	19	"5744285"	USPAT;	2004/01/16 09:23
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	4	"6392356"	USPAT;	2004/01/16 09:24
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	32	"5463191"	USPAT;	2004/01/16 09:25
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	268	glass adj1 (substrate or board) and (vias or (through near	USPAT;	2004/01/16 11:45
		holes)) and (display adj1 device) and driver	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	15	"5739463"	USPAT;	2004/01/22 09:23
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	

L Number	Hits	Search Text	DB	Time stamp
-	320	glass near (substrate or board) and (vias or (through near holes)) and filler	USPAT; US-PGPUB; EPO; DERWENT;	2004/01/22 09:23
-	30	glass near (substrate or board) and (vias or (through near holes)) and filler and (display near device)	IBM_TDB USPAT; US-PGPUB; EPO;	2003/08/20 15:55
-	49	361/760 and glass near (substrate or board) and (vias or (through near holes))	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO;	2003/08/20 15:55
-	8	("4574255" "5502889" "5854534" "5953213" "6052287"	DERWENT; IBM_TDB USPAT	2003/03/04 15:47
-	23	"6137167" "6333857" "6362525").PN. 361/748 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB;	2003/08/20 15:55
-	2 13	5912654.URPN. 361/750 and glass near (substrate or board) and (vias or (through near holes))	EPO; DERWENT; IBM_TDB USPAT USPAT; US-PGPUB; EPO;	2003/03/04 16:11 2003/08/20 15:55
-	11	361/751 and glass near (substrate or board) and (vias or (through near holes))	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO;	2003/08/20 15:55
-	18	361/761 and glass near (substrate or board) and (vias or (through near holes))	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; DERWENT;	2003/08/20 15:55
-	7	361/765 and glass near (substrate or board) and (vias or (through near holes))	IBM_TDB USPAT; US-PGPUB;	2003/08/20 15:56
-	14	361/767 and glass near (substrate or board) and (vias or (through near holes))	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO;	2003/08/20 15:56
-	6	361/768 and glass near (substrate or board) and (vias or (through near holes))	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO;	2003/08/20 15:56
-	11	361/772 and glass near (substrate or board) and (vias or (through near holes))	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO:	2003/08/20 15:56
-	219	glass near (substrate or board) and (vias or (through near holes)) and (display near device) and driver	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO;	2004/01/16 11:44
-	219	glass near (substrate or board) and (vias or (through near	EPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2

-	103	gandhi near jayprakash and electromagnetic and (holes or	USPAT;	2003/08/11 11:43
		apertures)	US-PGPUB;	
			EPO;	
	İ		DERWENT;	
			IBM_TDB	
-	38	glass near (substrate or board) and (vias or (through near	USPAT;	2003/08/20 16:13
		holes)) and filler and (display near device)	US-PGPUB;	
			EPO;	
	- 0		DERWENT;	
			IBM TDB	
_	52	361/760 and glass near (substrate or board) and (vias or	USPAT;	2003/08/20 15:56
		(through near holes))	US-PGPUB;	
		"	EPO:	
			DERWENT;	
1			IBM_TDB	
1_	26	361/748 and glass near (substrate or board) and (vias or	USPAT;	2003/08/20 15:57
	20	(through near holes))	US-PGPUB;	2000/00/20 10.0/
		(through hear holes))	EPO;	
		·	DERWENT;	
1		•		
	15	261/750 and gloss near (substrate or heard) and (vice or	IBM_TDB	2002/00/20 45:57
-	15	361/750 and glass near (substrate or board) and (vias or	USPAT;	2003/08/20 15:57
		(through near holes))	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	13	361/751 and glass near (substrate or board) and (vias or	USPAT;	2003/08/20 15:57
		(through near holes))	US-PGPUB;	
			EPO;	
		· ·	DERWENT;	
ļ			IBM_TDB	
-	16	361/761 and glass near (substrate or board) and (vias or	USPAT;	2003/08/20 15:57
		(through near holes))	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	8	361/765 and glass near (substrate or board) and (vias or	USPAT;	2003/08/20 15:57
		(through near holes))	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	19	361/767 and glass near (substrate or board) and (vias or	USPAT;	2003/08/20 15:57
		(through near holes))	US-PGPUB;	
			EPO;	
			DERWENT;	1
			IBM_TDB	
-	7	361/768 and glass near (substrate or board) and (vias or	USPAT;	2003/08/20 15:57
		(through near holes))	US-PGPUB;	
] · · · · · · · · · · · · · · · · · · ·	EPO;	
			DERWENT;	
			IBM_TDB	
-	10	361/772 and glass near (substrate or board) and (vias or	USPAT;	2003/08/20 15:57
		(through near holes))	US-PGPUB;	
		<u>'</u>	EPO;	
		·	DERWENT;	
			IBM_TDB	
-	1	roehling.in. and eves.in.	EPO; JPO;	2003/08/20 15:57
1	,		DERWENT	
_	344	glass near (substrate or board) and (vias or (through near	USPAT;	2004/01/16 09:22
	"	holes)) and filler	US-PGPUB;	2007/01/10 03.22
			EPO;	
			DERWENT;	
			IBM_TDB	
	<u></u>	L	<u> </u>	

-	109	349/\$ and glass near (substrate or board) and (vias or	USPAT;	2003/03/06 11:01
		(through near holes)) and (display near device) and driver	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
_	48	359/\$ and glass near (substrate or board) and (vias or	USPAT;	2003/03/06 11:37
		(through near holes)) and (display near device) and driver	US-PGPUB;	
		(through hour holds), and (display hour device) and anver	EPO;	
			DERWENT;	
			IBM TDB	
	42	313/\$ and glass near (substrate or board) and (vias or	_	2003/03/06 11:53
-	42	(through near holes)) and (display near device) and driver	USPAT;	2003/03/00 11.33
		(through near noies)) and (display hear device) and driver	US-PGPUB;	
			EPO;	
		,	DERWENT;	
			IBM_TDB	
-	1	"5739634".PN.	USPAT	2003/03/06 12:00
-	4	5739634.URPN.	USPAT	2003/03/06 12:02
-	0	6275254.URPN.	USPAT	2003/03/06 12:13
-	5	("4164683" "4410830" "5541478" "5736814"	USPAT	2003/03/06 12:13
		"5739634").PN.		
-	13	4164683.ÚRPN.	USPAT	2003/03/06 12:14
-	4	5150005.URPN.	USPAT	2003/03/06 12:15
_	9	5644327.URPN.	USPAT	2003/03/06 12:36
_	4	(alkali near glass near (substrate or board)) and (vias or	USPAT;	2003/03/06 12:52
	·	(through near holes)) and (display near device) and driver	US-PGPUB	
		through hear holes)) and (display hear device) and arrest	EPO;	
			DERWENT:	
	10	145/ft and place near (cubatrate or board) and (vice or	IBM_TDB	2002/02/06 12:50
-	19	445/\$ and glass near (substrate or board) and (vias or	USPAT;	2003/03/06 12:59
		(through near holes)) and (display near device) and driver	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
-	4	5597518.URPN.	USPAT	2003/03/06 13:03
-	34	4577133.URPN.	USPAT	2003/03/06 13:06
-	26	levi near dameon	USPAT;	2003/03/07 17:00
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
_	1	gandhi near jay	USPAT;	2003/03/07 17:00
		, , , , , , , , , , , , , , , , , , ,	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
<u>-</u>	656	gandhi near jayprakash	USPAT;	2003/08/11 11:42
		gandin near jayprakasii	US-PGPUB;	2000/00/11 11.42
		'	EPO;	
			DERWENT;	
		machling in and avec in	IBM_TDB	2002/00/20 45:57
-	1	roehling.in. and eves.in.	EPO; JPO;	2003/08/20 15:57
	_		DERWENT	0000/00//
-	0	2000236192.URPN.	USPAT	2003/08/11 11:23
-	1	roehling.in. and eves.in. and hewlett.as.	USPAT;	2003/08/20 15:56
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	166	gandhi near jayprakash and electromagnetic	USPAT;	2003/08/11 11:43
			US-PGPUB:	
			EPO;	
			DERWENT:	
			IBM_TDB	